

IEEE Wireless and Microwave Technology Conference

WAMICON 2019
April 8th and 9th 2019
Hilton Cocoa Beach
Cocoa Beach, Florida



Submission Deadline: Friday February 8, 2019

The 20th annual IEEE Wireless and Microwave Technology Conference (WAMICON 2019) will be held in Cocoa Beach, Florida on April 8th and 9th 2019. The conference will address up-to-date multidisciplinary research needs and interdisciplinary aspects of wireless and RF technology. The program includes both oral and poster presentations as well as tutorials and special sessions. Prospective authors are invited to submit original and high-quality work for presentation at WAMICON 2019 and publication in IEEE Xplore. Conference website is www.wamicon.org

TOPICS OF INTEREST INCLUDE

The central theme of WAMICON2019 will be ***“Simulation Driven Design of Emerging Wireless, Microwave and mm-Wave Circuits and Systems”***. Submissions on all aspects of related technologies, including antennas, passive and active circuits, communication theory, and system concepts, are encouraged.

mm-Wave to THz Technologies

5G Communications, Backhaul, MIMO and Massive MIMO, Beamforming, Vehicle-to-Everything (V2x), SatCom, Human Body Scanners, Radar, Home/Office Application, Electronic Warfare (EW), Tactical Networks/Data Links, Packaging, Integrated Circuits

Internet of Things (IoT)

Smart Homes, Smart Cities, Machine-to-Machine (M2M), Bluetooth Low Energy (BLE), Light Fidelity (Li-Fi), Near-Field Communication (NFC), RFID, Zigbee, Low-Power Wide-Area Network (LPWAN), Active Denial, Cognitive Radios and Software Defined Radios

Power Amplifiers, Other Active Components, and Systems

High-Efficiency PAs, Linearization and Efficiency Enhancement Techniques, Novel PA Architectures, High-Power Devices, Linear/Nonlinear Device Modeling, Reliability/Thermal Considerations, Transceiver Design, Multi-Band and Digital RF Circuits and Systems, System-On-Chip, System-In-Package, Radar RF/MMIC Electronics, Active Filters

Passive Components and Antennas

Filters, Transmission Line Components, MEMS, Advanced Packaging, Antennas and Arrays, Meta-Materials, Frequency Selective Surfaces, Non-Foster Impedance Matching

Microwave Applications

Biomedical Applications, Wireless Sensing, Energy Harvesting, Wireless Power Transfer, Radar, Additive Manufacturing, RF Applications in Space Exploration, Aerospace Applications of RF Circuits and Systems

PAPER SUBMISSION INSTRUCTIONS

Authors are asked to submit papers electronically in .PDF format. In order to be considered for publication by the Technical Program Committee, a submission of 3-4 pages, clearly describing the concept and results must be submitted before the deadline of February 8, 2019. The conference webpage at www.wamicon.org has complete details of submission requirements. Submissions will be evaluated for originality, significance of the work, technical soundness, and interest to a wide audience.

General Chair

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Papers Due: Fri., Feb. 8, 2019
Author Notification: Fri., Feb. 22, 2019
Final Papers Due: Fri., Mar. 1, 2019